

## Description

These N-Channel enhancement mode power field effect transistors are using split gate trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

## Features

- ◆ 40V,141A,  $R_{DS(on),max} = 2.8m\Omega @ V_{GS} = 10V$
- ◆ Improved dv/dt capability
- ◆ Fast switching
- ◆ 100% EAS Guaranteed
- ◆ Green device available

## Applications

- ◆ Motor Drives
- ◆ UPS
- ◆ DC-DC Converter

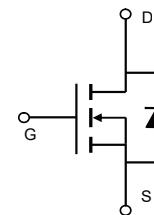
## Product Summary

$V_{DSS}$	40V
$R_{DS(on),max} @ V_{GS}=10V$	$2.8m\Omega$
$I_D$	141A

## Pin Configuration



TO-263



Schematic

## Absolute Maximum Ratings

 $T_c = 25^\circ C$  unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DSS}$	40	V
Continuous drain current ( $T_c = 25^\circ C$ )	$I_D$	141	A
( $T_c = 100^\circ C$ )		89	A
Pulsed drain current <sup>1)</sup>	$I_{DM}$	423	A
Gate-Source voltage	$V_{GSS}$	$\pm 20$	V
Avalanche energy <sup>2)</sup>	$E_{AS}$	36	mJ
Power Dissipation	$P_D$	89	W
Storage Temperature Range	$T_{STG}$	-55 to +150	$^\circ C$
Operating Junction Temperature Range	$T_J$	-55 to +150	$^\circ C$

## Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	1.4	$^\circ C/W$
Thermal Resistance Junction-to-Ambient	$R_{\theta JA}$	50	$^\circ C/W$

## Package Marking and Ordering Information

Device	Device Package	Marking	Units/Reel
VST04N028-T3	TO-263	VST04N028-T3	800

## Electrical Characteristics

T<sub>J</sub> = 25°C unless otherwise noted

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
<b>Static characteristics</b>						
Drain-source breakdown voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0 V, I <sub>D</sub> =250μA	40	---	---	V
Gate threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	1.2	1.7	2.5	V
Drain-source leakage current	I <sub>DSS</sub>	V <sub>DS</sub> =40 V, V <sub>GS</sub> =0V	---	---	1	μA
Gate leakage current, Forward	I <sub>GSSF</sub>	V <sub>GS</sub> =20 V, V <sub>DS</sub> =0 V	---	---	100	nA
Gate leakage current, Reverse	I <sub>GSSR</sub>	V <sub>GS</sub> =-20 V, V <sub>DS</sub> =0 V	---	---	-100	nA
Drain-source on-state resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =10 V, I <sub>D</sub> =20 A	---	2.2	2.8	mΩ
		V <sub>GS</sub> =4.5 V, I <sub>D</sub> =20 A	---	2.8	3.8	mΩ
Forward transconductance	g <sub>f</sub>	V <sub>DS</sub> =5V , I <sub>D</sub> =20A	---	55	---	S
<b>Dynamic characteristics</b>						
Input capacitance	C <sub>iss</sub>	V <sub>DS</sub> = 20 V, V <sub>GS</sub> = 0 V, F = 1MHz	---	3975	---	pF
Output capacitance	C <sub>oss</sub>		---	1123	---	
Reverse transfer capacitance	C <sub>rss</sub>		---	84	---	
Turn-on delay time	t <sub>d(on)</sub>	V <sub>DD</sub> = 15V, V <sub>GS</sub> =10V, I <sub>D</sub> = 20A R <sub>G</sub> =3.3Ω	---	18.7	---	ns
Rise time	t <sub>r</sub>		---	9.3	---	
Turn-off delay time	t <sub>d(off)</sub>		---	58.1	---	
Fall time	t <sub>f</sub>		---	32.5	---	
Gate resistance	R <sub>g</sub>	V <sub>GS</sub> =0 V, V <sub>DS</sub> =0 V, F=1MHz	---	1.1	---	Ω
<b>Gate charge characteristics</b>						
Gate to source charge	Q <sub>gs</sub>	V <sub>DS</sub> =15V, I <sub>D</sub> =20A, V <sub>GS</sub> = 10 V	---	12.3	---	nC
Gate to drain charge	Q <sub>gd</sub>		---	18.2	---	
Gate charge total	Q <sub>g</sub>		---	56	---	
<b>Drain-Source diode characteristics and Maximum Ratings</b>						
Continuous Source Current	I <sub>s</sub>	V <sub>GS</sub> =0V, I <sub>s</sub> =20A, T <sub>J</sub> =25°C	---	---	74	A
Pulsed Source Current <sup>3)</sup>	I <sub>SM</sub>		---	---	222	A
Diode Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>s</sub> =20A, T <sub>J</sub> =25°C	---	---	1.2	V

Notes:

1: Repetitive Rating: Pulse width limited by maximum junction temperature.

2: V<sub>DD</sub>=25V, V<sub>GS</sub>=10V, L=0.1mH, I<sub>AS</sub>=27A, Starting T<sub>J</sub>=25°C.

3: Pulse Test: Pulse Width ≤300 μ s, Duty Cycle≤2%.

## Electrical Characteristics Diagrams

Figure 1. Typ. Output Characteristics

Figure 2. Transfer Characteristics

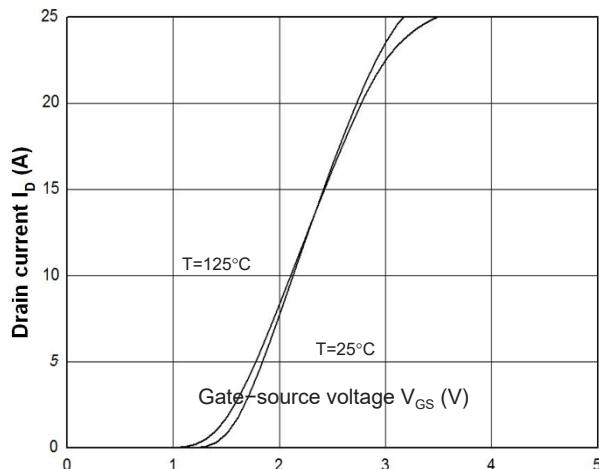


Figure 3. Capacitance Characteristics

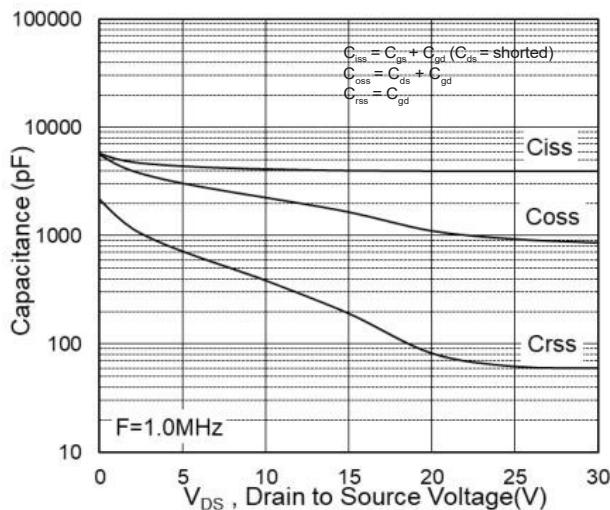


Figure 4. Gate Charge Waveform

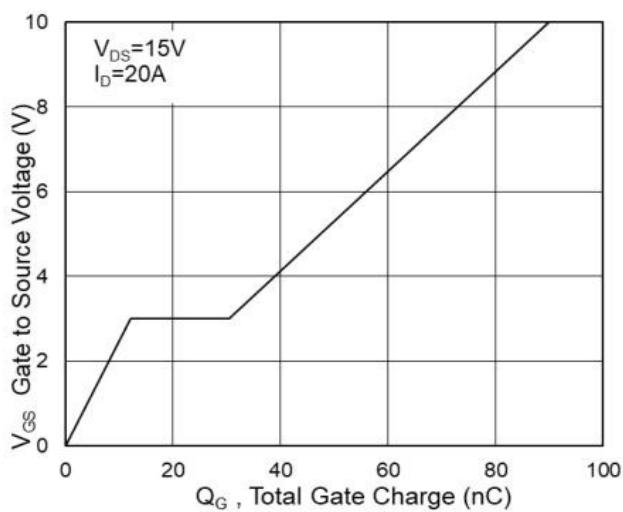


Figure 5. Body-Diode Characteristics

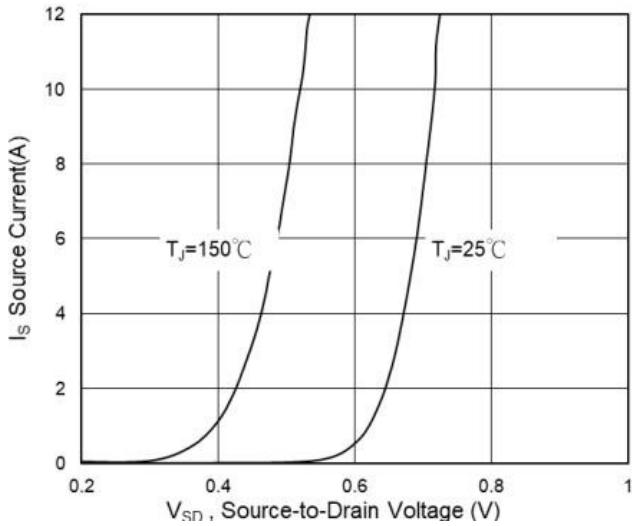


Figure 6. Rdson-Drain Current

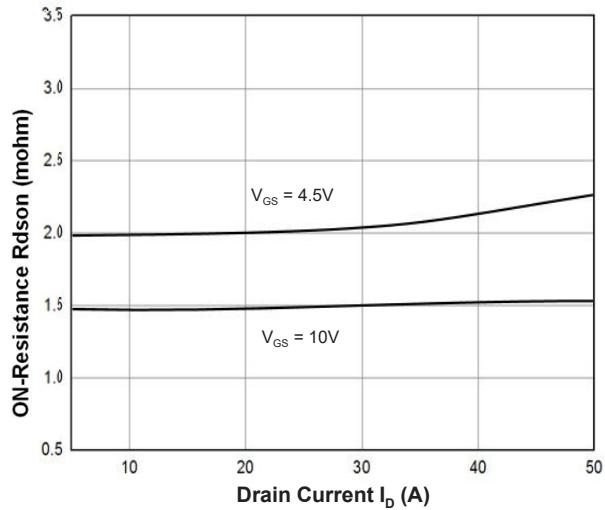


Figure 7. Rdson-Junction Temperature

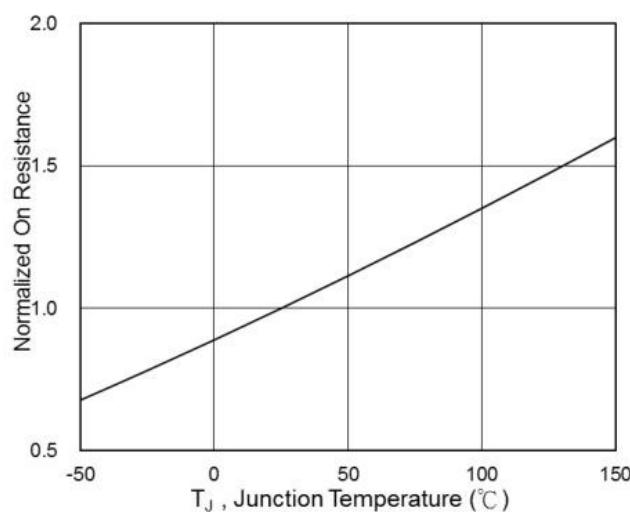


Figure 8.  $V_{GS(th)}$ -Junction Temperature

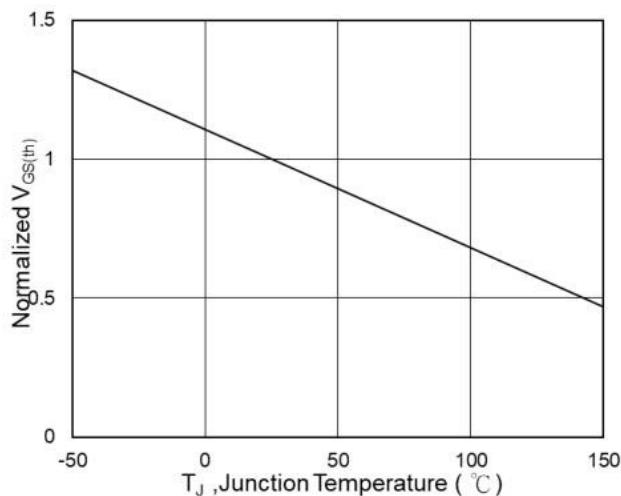


Figure 9. On-Resistance vs. Gate-to-Source voltage

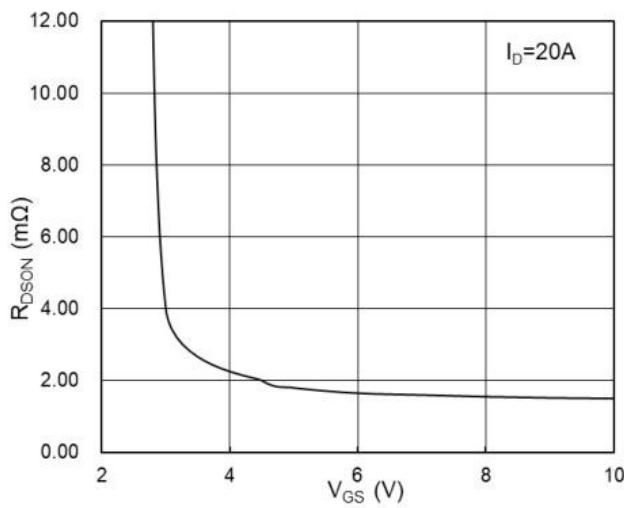


Figure 10: Safe Operating Area

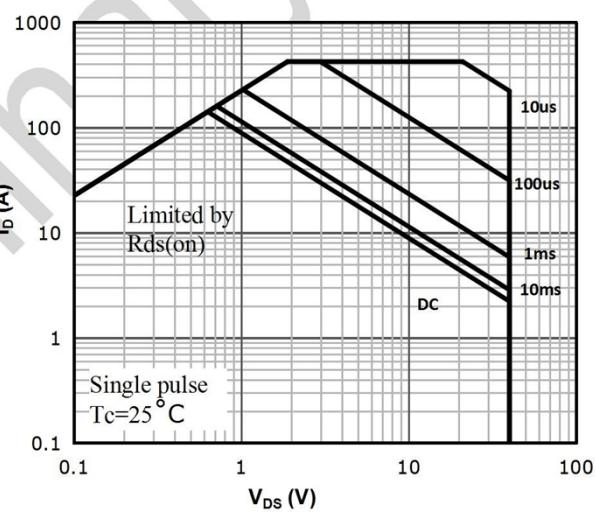
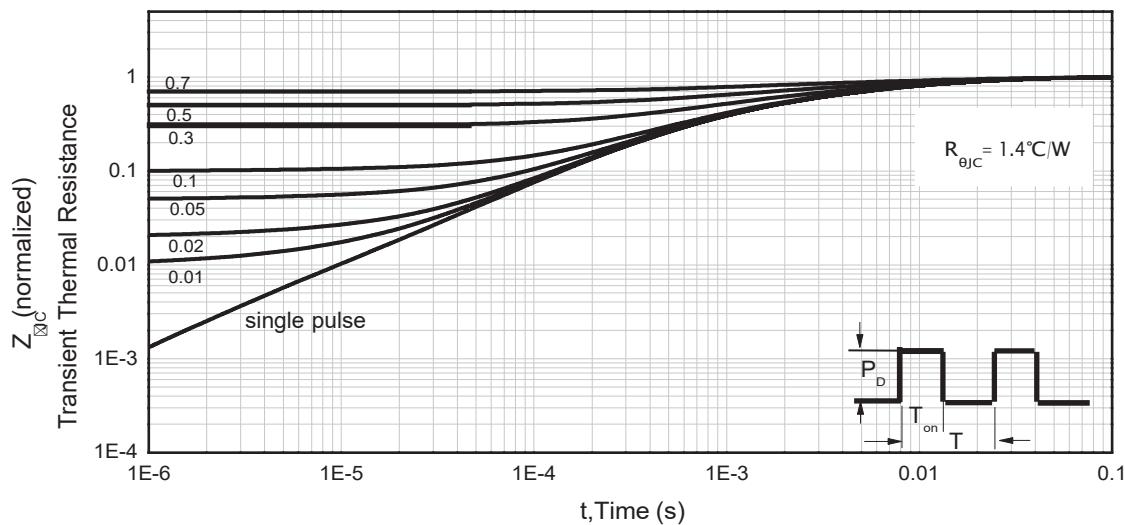
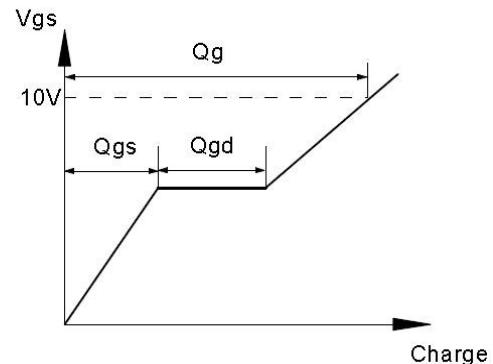
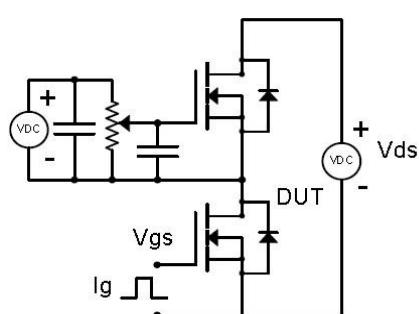


Figure 11. Normalized Maximum Transient Thermal Impedance (RthJC)

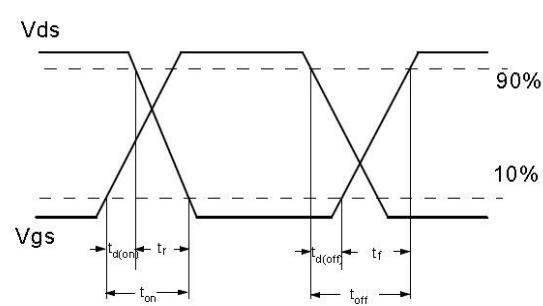
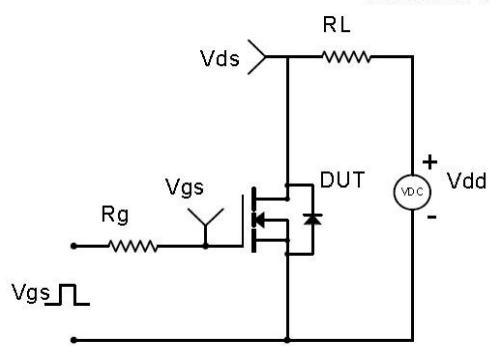


## Test Circuit & Waveform

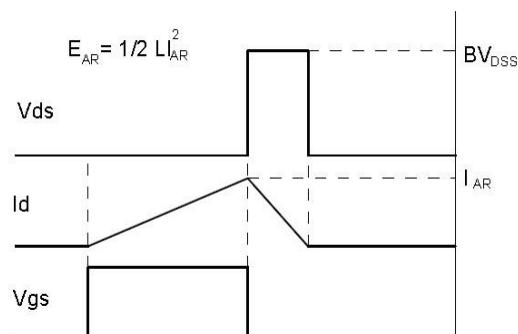
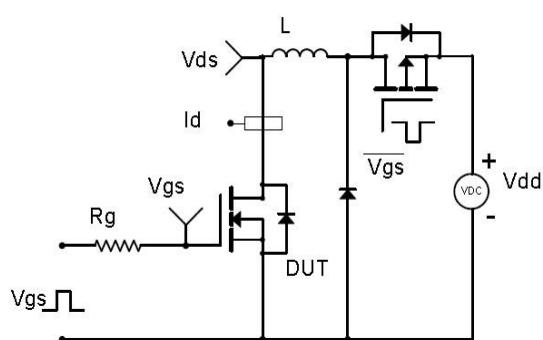
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms

